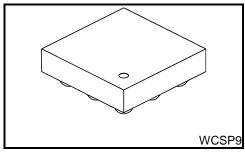
TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

## TCK301G, TCK302G, TCK303G

# 28 V, Single input – Single Output Load Switch IC with Over Voltage Protection

The TCK30 series are 28 V high input voltage Single Inputs—Single Output load switch ICs. It has Over Voltage Protection function featuring low switch ON resistance, high output current and wide input voltage operation. Switch ON resistance is only 73 m $\Omega$  at 4.5 V, - 1.0 A load conditions. And these feature a slew rate control driver, thermal shutdown and FLAG function. Also it can block reverse current if switch turned off. Output current is available up to 3 A. Thus this is suitable for power management such as Battery Charge application.

This device is available in 0.5mm pitch ultra small package WCSP9 (1.5 mm x 1.5 mm, t: 0.5 mm (Typ.)).Thus this devices is ideal for portable applications that require high-density board assembly such as cellular phone.

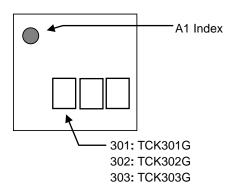


#### Weight: 3.5 mg (Typ.)

### Feature

- High input voltage: V<sub>IN</sub> (Max) = 28 V
- High output current: IOUT (DC) = 3.0 A
- Low ON resistance :  $R_{ON} = 73 \text{ m}\Omega$  (Typ.) at  $V_{IN} = 4.5 \text{ V}$ ,  $I_{OUT} = -1.0 \text{ A}$
- Over Voltage Lockout : 6.6 V, 10.5 V, and 15.5 V (Typ.)
- Under Voltage Lockout: 2.9 V (Typ.)
- FLAG indicates
- Internal 15 ms startup hold
- Reverse current blocking (SW OFF state)
- Inrush current reducing circuit
- Thermal Shutdown function
- Small package: 0.5 mm pitch WCSP9 (1.5 mm x 1.5 mm, t: 0.5 mm (Typ.)), PD = 1.65 W

### **Top marking**



Start of commercial production 2015-05

### Absolute Maximum Ratings (Ta = 25°C)

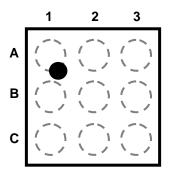
Characteristics	Symbol	Rating			Unit						
Input voltage	VIN	-0.3 to 30			-0.3 to 30		-0.3 to 30		-0.3 to 30		V
Control voltage	VCT, VCE	-0.3 to 6			-0.3 to 6		V				
Output voltage	Vout	-0.3 to 18		-0.3 to 18							
Flag voltage	VFLAG	-0.3 to 6		-0.3 to 6		V					
Output current	IOUT	DC	3.0		•						
		Pulse	4.0	(Note 1)	A						
Power dissipation	PD	1.65		(Note 2)	W						
Operating temperature range	T <sub>opr</sub>	-40 to 85		-40 to 85							
Junction temperature	Тј	150		150		150		°C			
Storage temperature	T <sub>stg</sub>	-55 to 150		-55 to 150		-55 to 150		°C			

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: 1 ms pulse, 1% duty cycle

Note2: Rating at mounting on a board: FR4 board. (  $40 \text{ mm} \times 40 \text{ mm} \times 1.6 \text{ mm}$ , Cu 4 layer )

### Pin Assignment (Top view/Bottom bump)



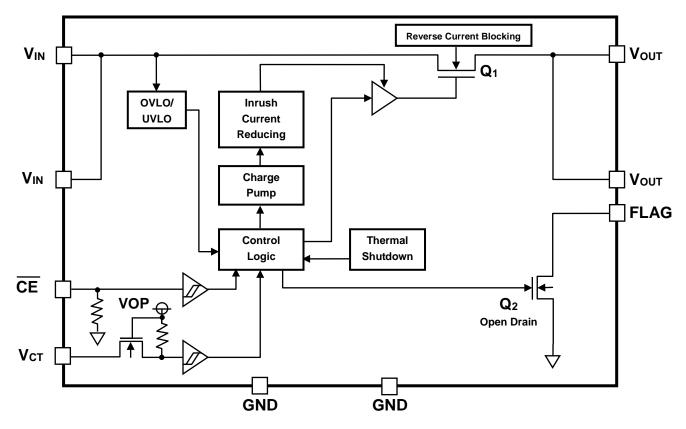
	1	2	3
Α	FLAG	V <sub>CT</sub>	CE
В	V <sub>IN</sub>	GND	V <sub>OUT</sub>
С	V <sub>IN</sub>	GND	Vout

### **Product list**

Part number	Over voltage lockout	CE function	VCT function	VCT resistance
TCK301G	6.6 V (Typ.)	Active Low	Active High	Pull up
TCK302G	10.5 V (Typ.)	Active Low	Active High	Pull up
TCK303G	15.5 V (Typ <b>.</b> )	Active Low	Active High	Pull up

Please ask your local retailer about the devices with other OVLO, logic function and pull up resistance.

### **Block Diagram**



### **PIN Description**

PIN	Name	Description
A1	FLAG	Open drain acknowledge signal output. When input voltage is in regular range ( $V_{UVL}$ < $V_{IN}$ < $V_{OVL}$ ), $Q_2$ turn ON. FLAG output turn to be high impedance in irregular input voltage range, $\overline{CE}$ High state and thermal shutdown operation.
A2	Vcт	Switch Control function. It is internally connected to VOP (Pull up).
A3	CE	Chip Enable function. It is internally connected to GND(Pull down).
B1, C1	V <sub>IN</sub>	Input. It has Over Voltage Lock Out (OVLO) and Under Voltage Lock Out function (UVLO).
B2, C2	GND	Ground
B3, C3	Vout	Output

### **Operation Logic Table**

### TCK301G, TCK302G, TCK303G

		CE "Low"	CE " High"
	Q₁ (Main Switch)	ON	OFF
V <sub>ст</sub> "HIGH	Q₂(FLAG out)	ON (When V <sub>UVL</sub> < V <sub>IN</sub> < V <sub>OVL</sub> ), OFF (When V <sub>UVL</sub> > V <sub>IN</sub> , or V <sub>IN</sub> > V <sub>OVL</sub> ), OFF (Thermal shut down = active)	OFF
	Reverse current block	Disable	Active
Vст "LOW"	Q₁ (Main Switch)	OFF	OFF
	Q₂(FLAG out)	ON (When V <sub>UVL</sub> < V <sub>IN</sub> < V <sub>OVL</sub> ), OFF (When V <sub>UVL</sub> > V <sub>IN</sub> , or V <sub>IN</sub> > V <sub>OVL</sub> ), OFF (Thermal shut down = active)	OFF
	Reverse current block	Active	Active

### DC Characteristics (Ta = -40 to 85°C)

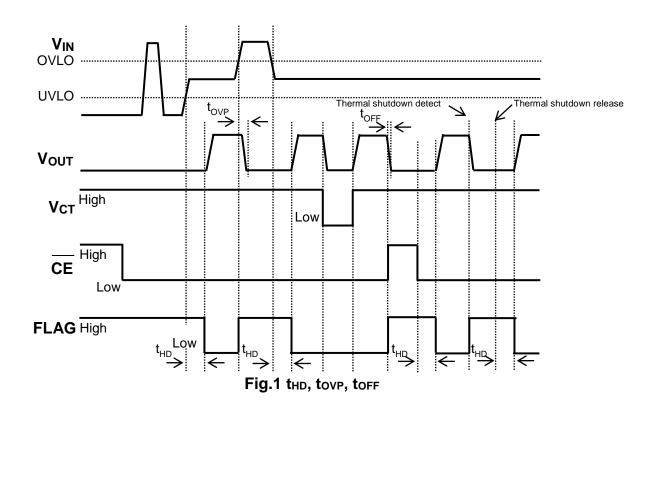
		Test Condition		Ta = 25°C			Ta = −40 to 85°C		
Characteristics	Symbol		Min	Тур.	Max	Min	Max	Unit	
Input voltage	VIN	—	2.3	—	28	2.3	28	V	
CE,V <sub>CT</sub> High-level input voltage	VIH	V <sub>IN</sub> = 2.3 to 28 V	1.6	_	_	1.6	_	V	
CE,V <sub>CT</sub> Low-level input voltage	VIL	V <sub>IN</sub> = 2.3 to 28 V	—	_	0.3	—	0.3	V	
		TCK301G	—	6.6	—	5.9	7.3		
Over voltage lock out (OVLO) rising threshold	Vovl_ri	TCK302G	—	10.5	—	9.1	11.9	V	
Ŷ		TCK303G	—	15.5	_	13.9	17.1		
Over voltage lock out (OVLO)		ТСК301G	_	V <sub>OVL_RI</sub> _ 0.35	_	_	_	v	
falling threshold	Vovl_fa	TCK302G, TCK303G	—	Vovl_ri _ 0.5	_	_	-	v	
Under voltage lock out (UVLO) rising threshold	VUVL_RI	_	_	2.9	_	2.3	3.5	V	
Under voltage lock out (UVLO) falling threshold	VUVL_FA	_	_	V <sub>UVL_RI</sub> _ 0.3	_	_	_	V	
Quiescent current (ON state)	IQ(ON)	CE         = Open, VCT = Open           IOUT = 0 mA,         VIN = 5.0 V	_	130	_	_	190	μA	
Quiescent current (OFF state)	IQ(OFF1)		_	75	_	_	115	μA	
Input Shutdown Current	IQ(OFF2)	$\label{eq:cell} \begin{array}{l} \overline{\text{CE}} = 3.0 \text{ V}, \text{ V}_{\text{CT}} = \text{ Open}, \\ \text{V}_{\text{IN}} = 5.0 \text{ V}, \text{ V}_{\text{OUT}} = 0 \text{ V} \end{array}$	_	1.3	_	_	10	μΑ	
Switch OFF state current	IOFF	$\label{eq:cell} \begin{array}{l} \overline{CE} \texttt{=} \texttt{3.0} \texttt{V}, \texttt{V}_{CT} \texttt{=} \texttt{Open}, \\ \texttt{V}_{IN} \texttt{=} \texttt{Open},  \texttt{V}_{OUT} \texttt{=} \texttt{5} \texttt{V} \end{array}$	_	0.1	_	_	1	μA	
Reverse blocking current	I <sub>RB</sub>	Vout = 5.0 V, VIN = 0 V, Vct = 0 V	_	0.1	_	_	10	μA	
On resistance	Ron	$I_{OUT} = -1.0 \text{ A}, \text{ V}_{IN} = 4.5 \text{ V}$	_	73	—	_	140	mΩ	
FLAG Leak current	ILEAK	$V_{IO} = 5.0 \text{ V}$		_	2	_	2	μΑ	
FLAG Output low voltage	V <sub>OL</sub>	$I_{SINK} = 1 \text{ mA}, V_{IO} = 5.0 \text{ V}$	—	_	0.4	_	0.4	V	
CE built-in resistance	RCE	_	_	530	_	_	—	ko	
VCT built-in resistance	Rvct	-	_	530		_	_	kΩ	

### AC Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition (Figure 1, 2)		Тур.	Max	Unit
Hold time	tHD	$V_{UVL}$ < $V_{IN}(5V)$ < $V_{OVL}$ , $R_L$ = 50 $\Omega$ Initial start up $V_{OUT}$ off state to charge-pump on state	_	15	_	ms
V <sub>OUT</sub> OVP off time	tOVP	$V_{IN} > V_{OVLO_RI}$ , $V_{IN}$ rising = 2V/µs, RL = 50 $\Omega$ , $V_{OUT}$ to 80% of $V_{OVLO_RI}$	_	3	_	μS
V <sub>OUT</sub> off time	tOFF	$V_{UVL} < V_{IN} (5V) < V_{OVL}, R_L = 50 \ \Omega,$ $V_{OUT} \text{ to } 80\% \text{ of } V_{IN}$	_	2	_	μS
V <sub>OUT</sub> rise time	tr	$V_{\text{IN}}\text{=}5.0\text{V}$ , $\text{R}_{\text{L}}\text{=}50~\Omega$ , $\text{C}_{\text{L}}\text{=}1.0~\text{uF}$	_	2	_	ms
V <sub>OUT</sub> fall time	t <sub>f</sub>	$V_{\text{IN}}\text{=}5.0\text{V}$ , $\text{R}_{\text{L}}\text{=}50~\Omega$ , $\text{C}_{\text{L}}\text{=}1.0~\text{uF}$	-	0.12	_	ms
V <sub>CT</sub> delay time (Enable to Disable)	tCT1	$V_{IN}$ = 5.0V , R <sub>L</sub> = 50 $\Omega$	—	0.5	—	μs
VCT delay time (Disable to Enable)	tCT2	$V_{IN}$ = 5.0V , $R_L$ = 50 $\Omega$	_	3.2	—	ms

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**Timing chart** 



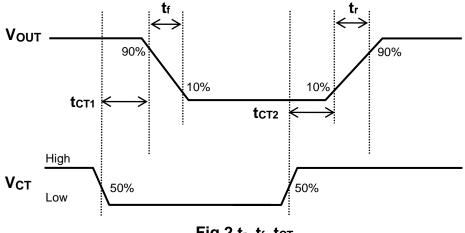
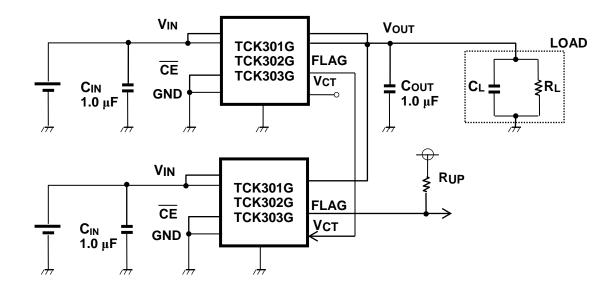


Fig.2 tr, tf, tcT

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### **Application Note**

1. Application circuit example (top view)



1) Input and Output capacitor

An input capacitor ( $C_{IN}$ ) and an output capacitor ( $C_{OUT}$ ) are necessary for the stable operation of TCK301G, TCK302G and TCK303G. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  and  $C_{OUT}$  more than 1.0µF as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) Control pin

Control pins for TCK301G, TCK302G and TCK303G is operated by the control voltage and Schmitt trigger.  $V_{CT}$  pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

### 2. Reverse current blocking

Reverse current blocking (SW OFF state) function is designed in these products. This function is active at output n-ch MOSEFT turned off.

However these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.

### 3. Thermal shut down function

Thermal shutdown function is designed in these products, but these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.

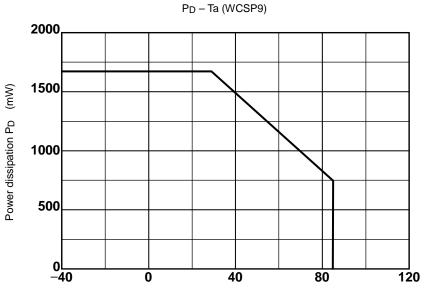


#### 4. Power Dissipation

Board-mounted power dissipation ratings for TCK301G, TCK302G and TCK303G are available in the Absolute Maximum Ratings table.

Power dissipation is measured on the board condition shown below.

[The Board Condition] Board material: Glass epoxy (FR4) Board dimension: 40 mm x 40 mm (Cu 4 layer)

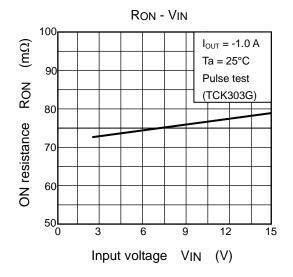


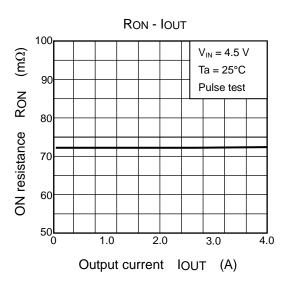
Ambient temperature Ta (°C)

Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc. and applying the appropriate derating for allowable power dissipation during operation.

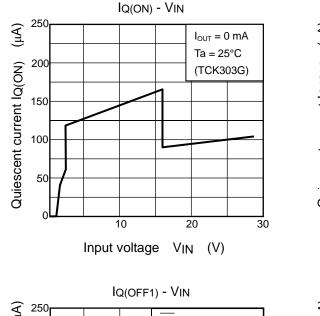
### **Representative Typical Characteristics**

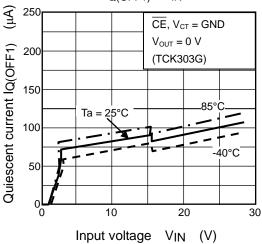
### 1) ON resistance



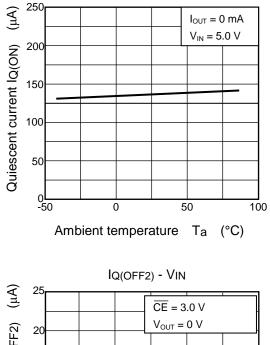


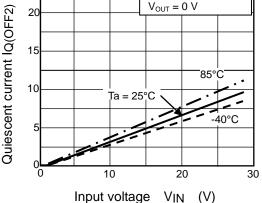
### 2) Quiescent current





IQ(ON) - Ta



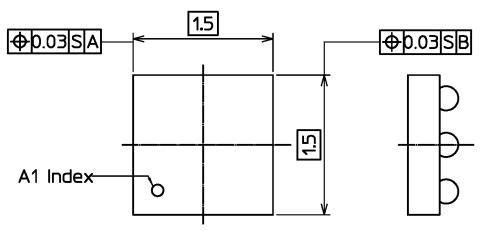


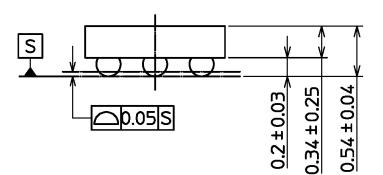
### **TOSHIBA**

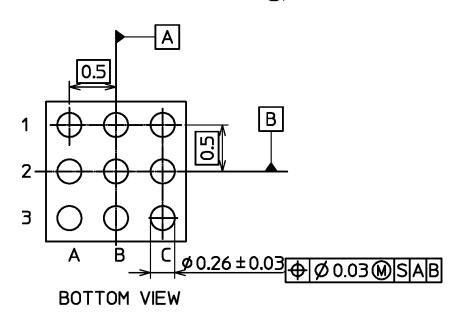
### **Package Dimensions**

WCSP9

Unit: mm



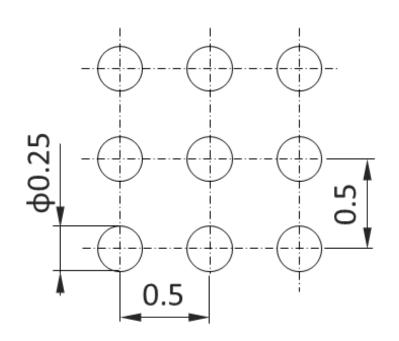




Weight: 3.5 mg (Typ.)

Land pattern dimensions (for reference only)

Unit: mm



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